

1.6X0.8mm SMD CHIP LED LAMP (0.25mm Height)

Part Number: APG1608CGKC/T

Green

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ERP: 1203008081

Features

- 1.6mmX0.8mm SMT LED, 0.25mm thickness.
- Low power consumption.
- Wide viewing angle.
- Compatible with automatic placement equipment.
- Ideal for backlight and indicator.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

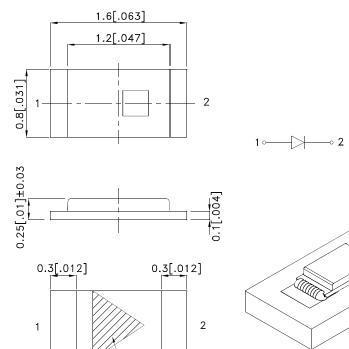
Description

The Green source color devices are made with AlGaInP on GaAs substrate Light Emitting Diode.

Applications

- 1. Mobile phone Keypad indicator and backlight.
- 2.Flat backlight for LCD, switch and symbol.
- 3.Toys.

Package Dimensions



- 1. All dimensions are in millimeters (inches)
- 2. Tolerance is ±0.1(0.004") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice 4. The device has a single mounting surface. The device must be mounted according to the specifications.

POLARITY

MARK

SPEC NO: DSAI5959 **REV NO: V.3 DATE: SEP/28/2010** APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: J.Yu

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		,,	Min.	Тур.	201/2
APG1608CGKC/T	Green (AlGaInP)	Water Clear	36	70	120°

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Green	574		nm	IF=20mA
λD [1]	Dominant Wavelength	Green	570		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Green	15		nm	IF=20mA
С	Capacitance	Green	15		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Green	2.1	2.6	V	I=20mA
IR	Reverse Current	Green		10	uA	V _R =5V

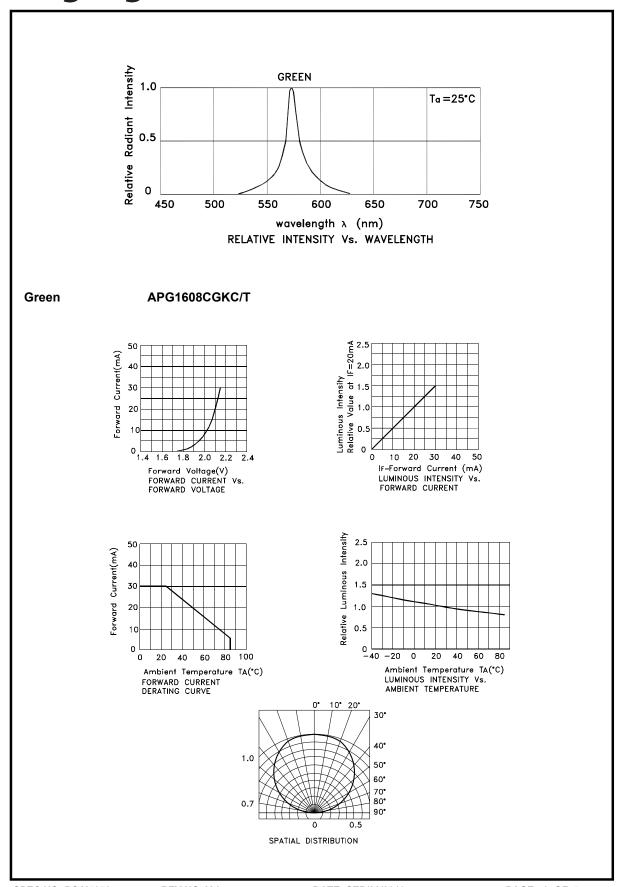
- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Green	Units	
Power dissipation	78	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

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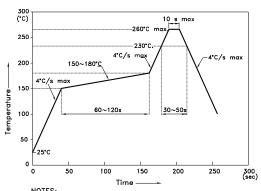
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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

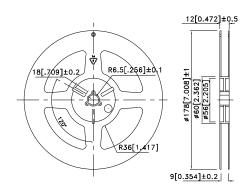
0.8

0.8

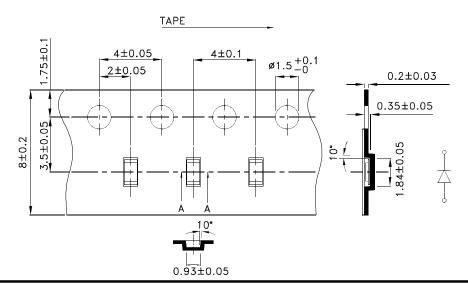
0.85

0.8

Reel Dimension

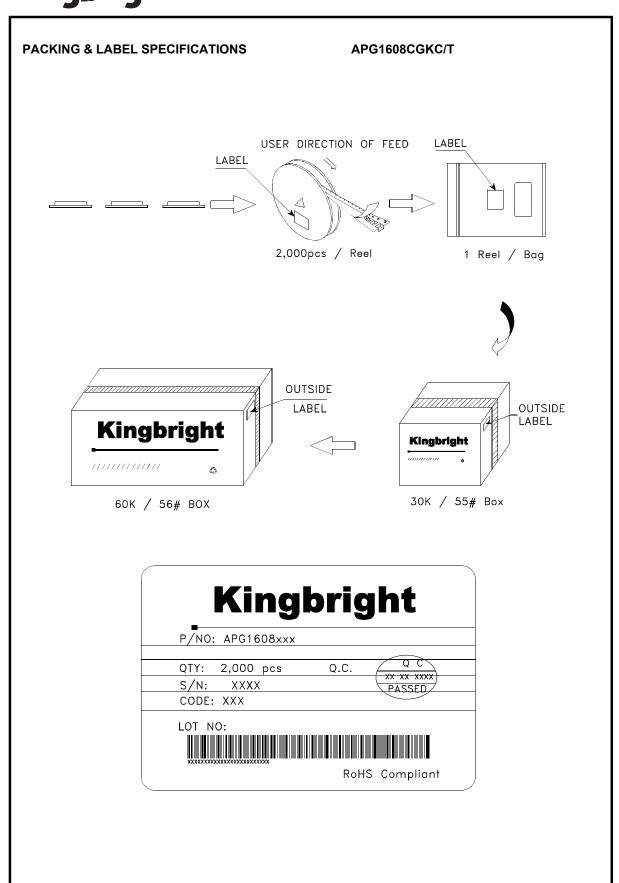


Tape Dimensions (Units: mm)



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